

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

Claims 1-8 (canceled).

9. (currently amended): A wiring substrate comprising:

a core substrate including an insulating substrate, a through hole provided through the insulating substrate, a substantially cylindrical through hole conductoreconductors formed on an inner circumference of said through hole, and a filling material filling a hollow portion of said through hole conductoreconductors;

a cover-shaped conductor layer provided on at least one principal face of said core substrate and in a shape containing an end face of said through hole and having conduction to said through hole conductor;

a plurality of resin layers provided over said cover-shaped conductor layer;

a ball pad conductor provided over said resin layers and having a solder ballballs to be connected with a connection terminalterminals of an external device; and

a connection portion including via conductors buried individually in said resin layers for bringing said cover-shaped conductor layer and said ball pad conductor into conduction,

wherein the connection portion comprises a conformal viaconductor of said connection portion, which is connected to said cover-shaped conductor layer and one or more filled vias connecting said conformal via to said ball pad, is composed of conformal vias whereas

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~~the remaining via conductors are composed of filled vias~~, said conformal vias having a hole wall, a metallic material arranged along the hole wall, and a resin material filling the remaining portion of the hole, and

~~taking in case~~ a through direction of said through hole ~~as being~~ is a center axis direction, an individual center axes of said via conductor composed of said one or more filled vias and said ball pad conductor are not aligned with the center axis of said through hole.

10. (canceled).
11. (canceled).
12. (canceled).
13. (currently amended): The wiring substrate according to claim 9, wherein said filling material filling a hollow portion of said through hole ~~conductors~~ conductor comprises a resin.
14. (canceled).
15. (canceled).
16. (new): The wiring substrate according to claim 9, wherein the one or more filled vias constituting the connection portion each has a center axis that is spaced by 50 μm or more and 300 μm or less from a center axis of the through hole.
17. (new): The wiring substrate according to claim 9, wherein said conformal via is connected to an upper side principal face of the cover-shaped conductor layer.